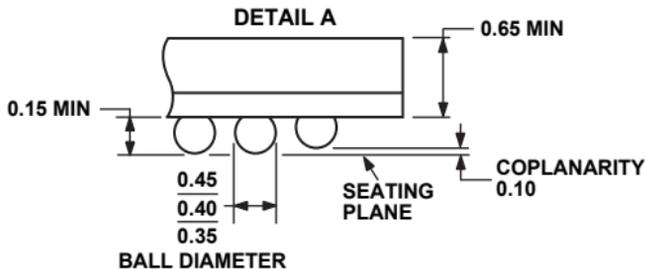
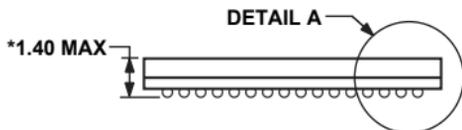
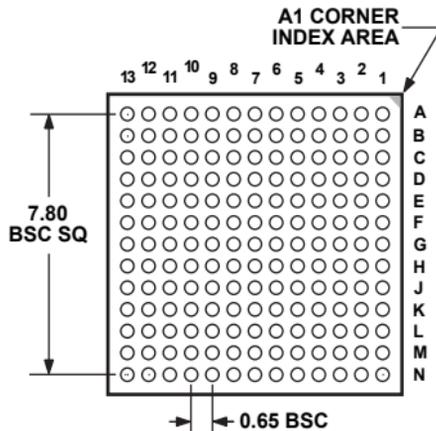
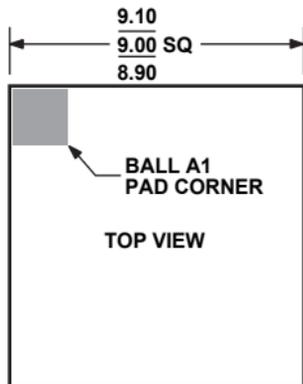


169-Ball Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-169)

Dimensions shown in millimeters



***COMPLIANT TO JEDEC STANDARDS MO-225
WITH THE EXCEPTION TO PACKAGE HEIGHT.**